

## 30 GHz Clock Distributor

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### Features

- Wideband operation: 5 GHz – 30 GHz
- Single-ended clock input
- 2 differential outputs
- Output Amplitude: 0.9 V<sub>pp</sub> (Typ.)

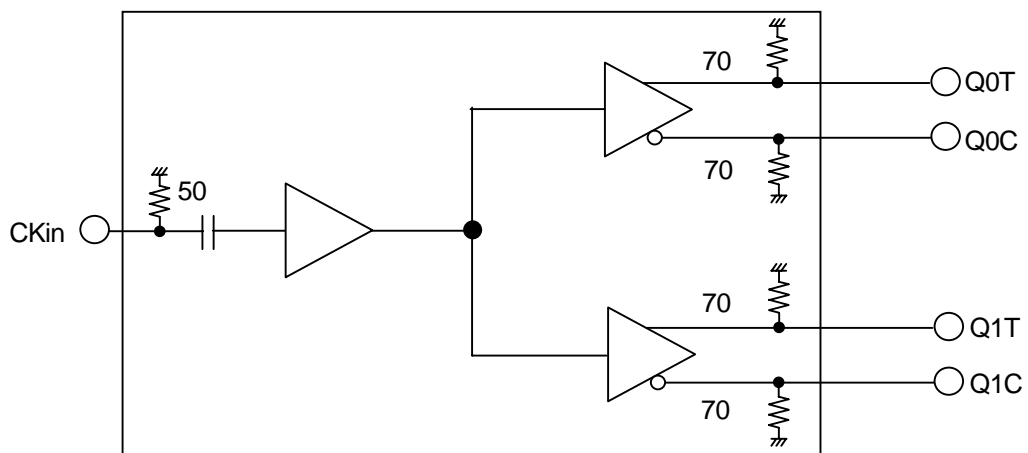
### General Description

The CI0403 is an ultra-fast 1:2 Clock Distributor operating at rates up to 30 GHz. The IC is fabricated using a 0.1- $\mu$ m InP HEMT process. The CI0403 is provided in a hermetically-sealed package with V-connectors.

### Applications

- Clock Distributor
- Clock Amplifier

### Functional Diagram



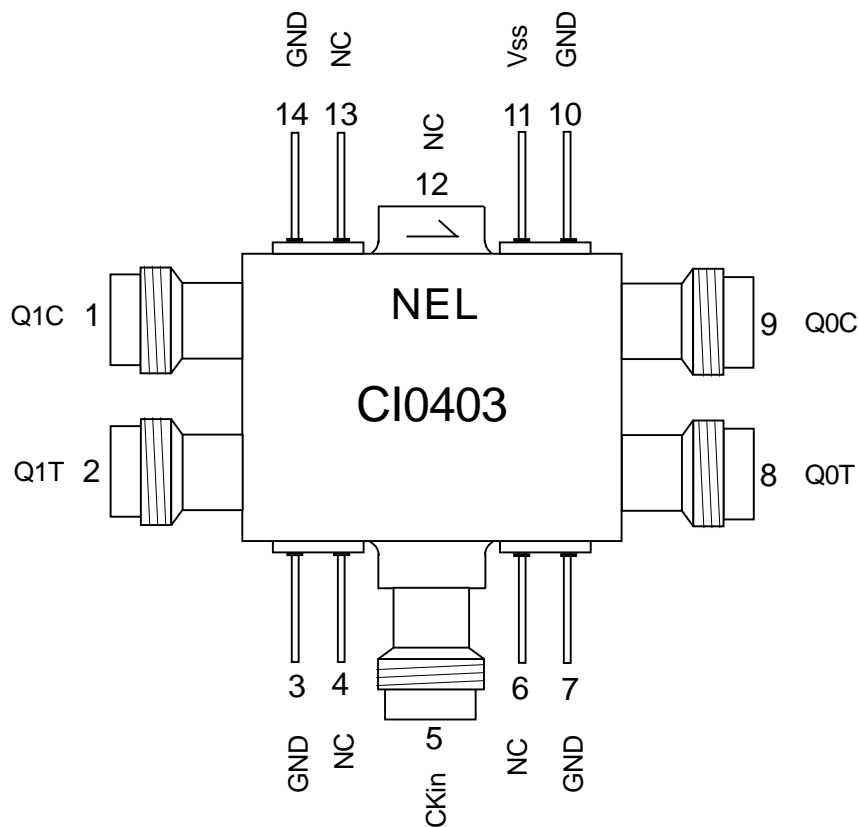
### Connection Table

No.	NAME	FUNCTION	No.	NAME	FUNCTION
1	Q1C <sup>(1)</sup>	Clock Output 1 (Complementary)	8	Q0T <sup>(1)</sup>	Clock Output 0 (True)
2	Q1T <sup>(1)</sup>	Clock Output 1 (True)	9	Q0C <sup>(1)</sup>	Clock Output 0 (Complementary)
3	GND	Ground (0.0 V)	10	GND	Ground (0.0 V)
4	NC	No Internal Connection	11	Vss	Power Supply (-4.5 V)
5	CKin	Clock Input	12	NC	No Internal Connection
6	NC	No Internal Connection	13	NC	No Internal Connection
7	GND	Ground (0.0 V)	14	GND	Ground (0.0 V)

Notes

- (1) Terminate unused output connectors to GND through 50-ohm resistors.

### Connection Diagram (Top View)



## Absolute Maximum Ratings

SYMBOL	PARAMETER	RATING	UNIT
VSS	Power Supply Voltage	-5.0 to +0.1	V
Vin	Applied Voltage Amplitude at Clock Input (CKin)	1.2	Vpp
Vinck	Applied Voltage at Clock Input (CKin)	-1.2 to +1.2	V
Vout	Applied Voltage at Clock Outputs (Q0T, Q0C, Q1T, Q1C)	TBD	V
Tstor	Storage Temperature	TBD	°C
Tc <sup>(1)</sup>	Case Temperature under Bias	TBD	°C

TBD: To Be Determined

## Recommended Operating Conditions

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
VSS	Power Supply	-4.7	-4.5	-4.3	V
CKin	Clock Input Interface	DC coupling or AC coupling (see AC Characteristics)			
Q0T, Q0C Q1T, Q1C	Data Output Interface	DC coupling (see AC Characteristics), Terminate to GND through 50 ohm.			

## DC Characteristics

(VSS = -4.5 V, GND = 0.0 V, Tc<sup>(1)</sup> = 30 °C)

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
ISS	Power Supply Current		260	TBD	mA

TBD: To Be Determined

Note

(1) Tc: Temperature at package base.

## AC Characteristics

(V<sub>SS</sub> = -4.5 V, GND = 0.0 V)

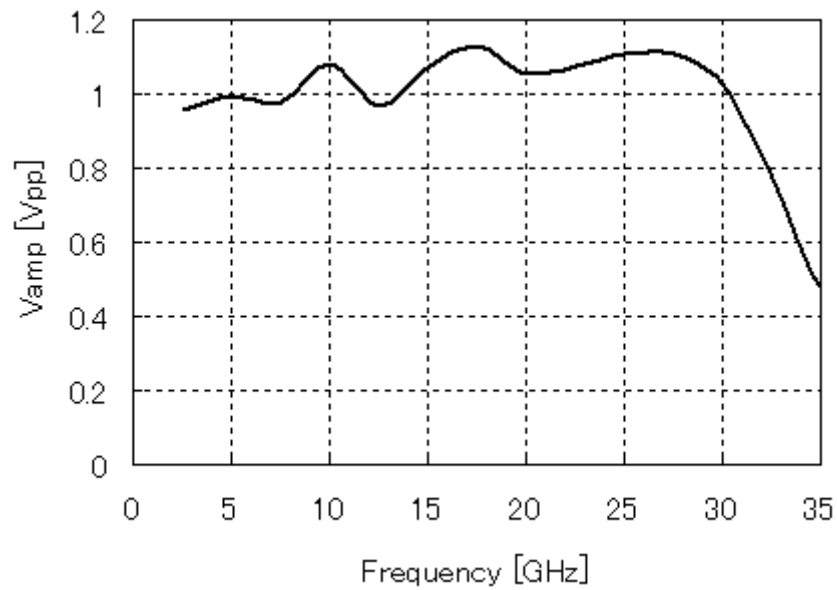
SYMBOL	PARAMETER	T <sub>c</sub> =30 °C			UNIT
		MIN	TYP	MAX	
V <sub>in</sub>	Clock Input Voltage Amplitude	TBD	0.6		V <sub>pp</sub>
V <sub>center</sub>	Clock Input Center Voltage	-0.6		0.6	V
f <sub>MAX</sub>	Maximum Input frequency	30			GHz
f <sub>MIN</sub>	Minimum Input frequency			5	GHz
V <sub>amp</sub>	Output Voltage Amplitude (Q0T, Q0C, Q1T, Q1C)	TBD	0.9		V <sub>pp</sub> (1)
t <sub>r</sub>	Output Rise Time (Q0T, Q0C, Q1T, Q1C) 20 - 80%		9	TBD	ps (2)
t <sub>f</sub>	Output Fall Time (Q0T, Q0C, Q1T, Q1C) 20 - 80%		9	TBD	ps (2)
Jitter	Output jitter (Q0T, Q0C, Q1T, Q1C)			0.03	UI <sub>rms</sub> (3)

(1) Measurement Condition: f = 30 GHz

(2) Measurement Condition: f = 10 GHz

$$(3) \text{ Jitter}[UI_{rms}] = \frac{\sqrt{(\text{OutputRMSJitter})^2 - (\text{InputRMSJitter})^2}}{1/f}$$

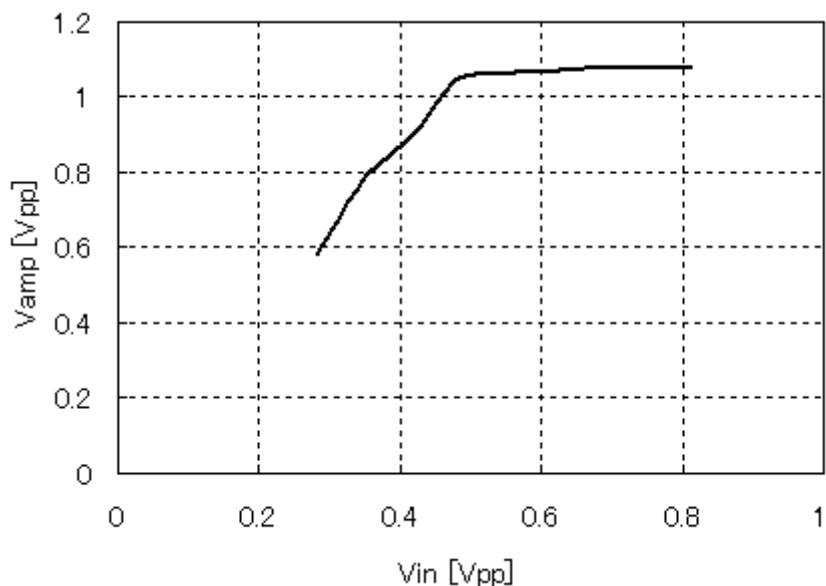
### Sample Output Voltage Amplitude vs. Frequency (2.5GHz – 35GHz)



#### Measurement Conditions

$V_{ss} = -4.5$  V,  $V_{in} = 0.6$  Vpp

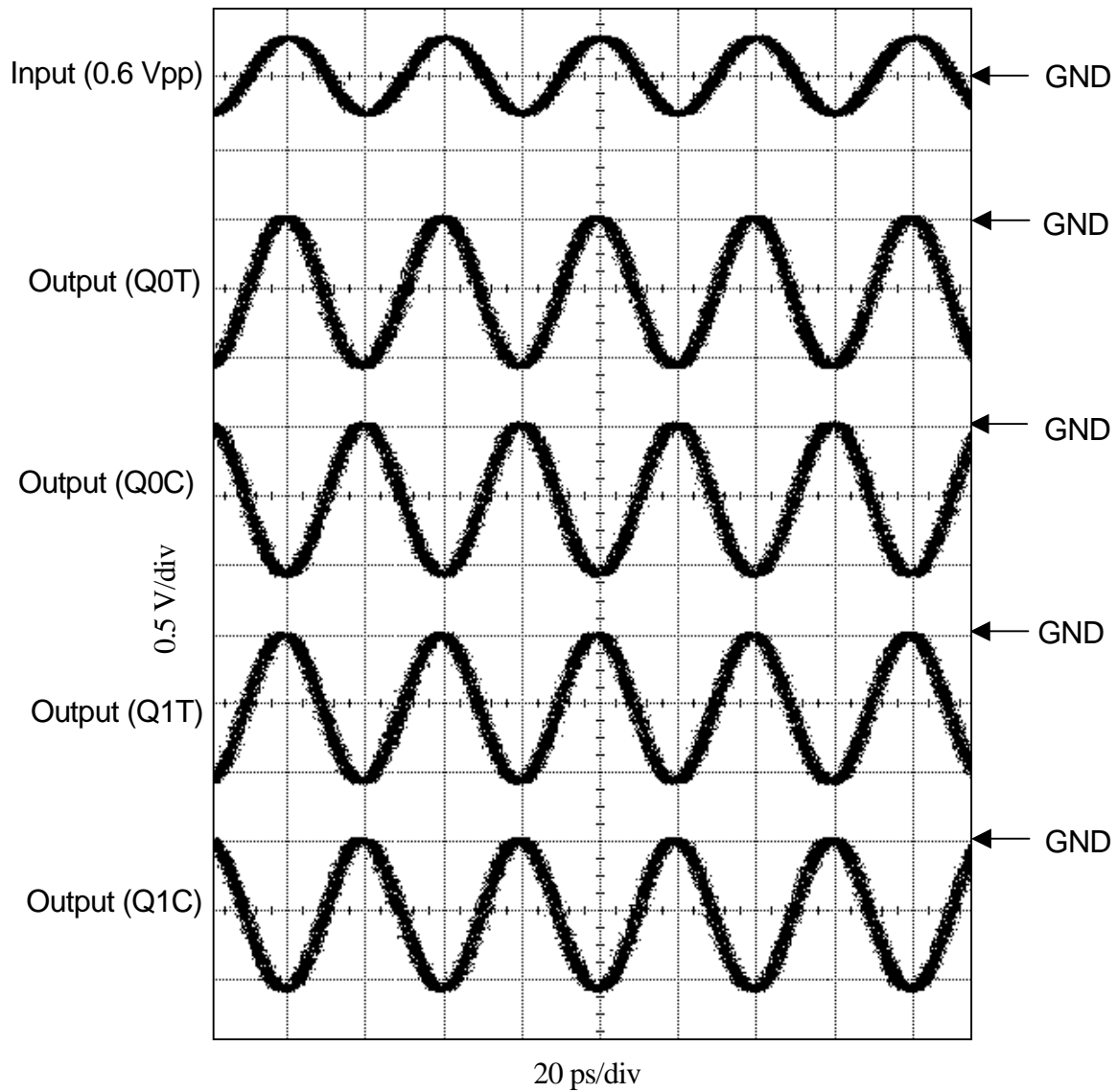
### Sample Output Voltage Amplitude vs. Input Voltage Amplitude at 25 GHz



#### Measurement Conditions

$V_{ss} = -4.5$  V, Input Clock : 25GHz

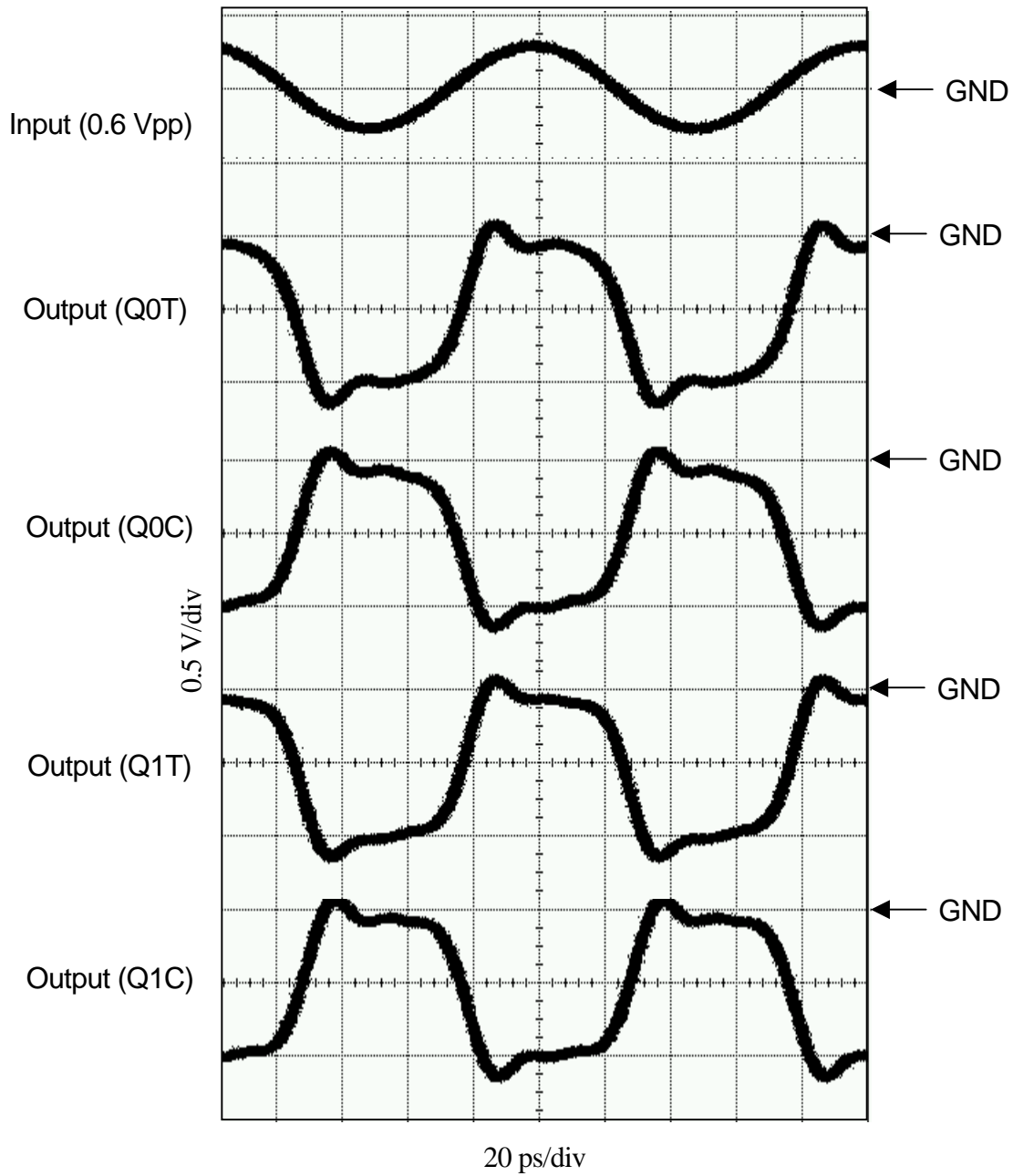
### Sample Waveforms (25 GHz)



#### Measurement Conditions

V<sub>ss</sub> = -4.5 V, Input Clock: 25 GHz , 0.6V<sub>pp</sub>

### Sample Waveforms (10 GHz)

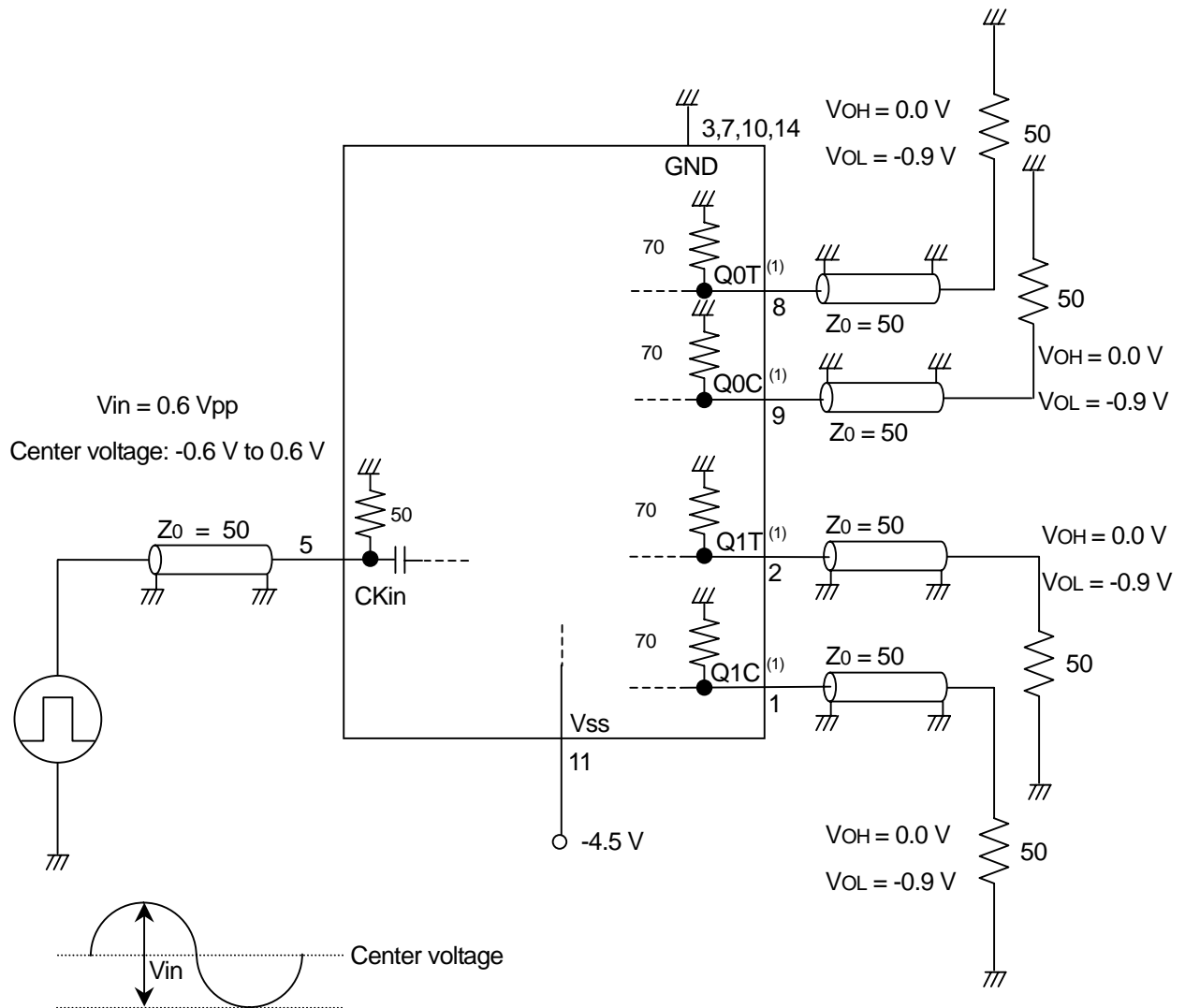


#### Measurement Conditions

$V_{ss} = -4.5 \text{ V}$ , Input Clock: 10 GHz , 0.6Vpp

## Sample Implementation

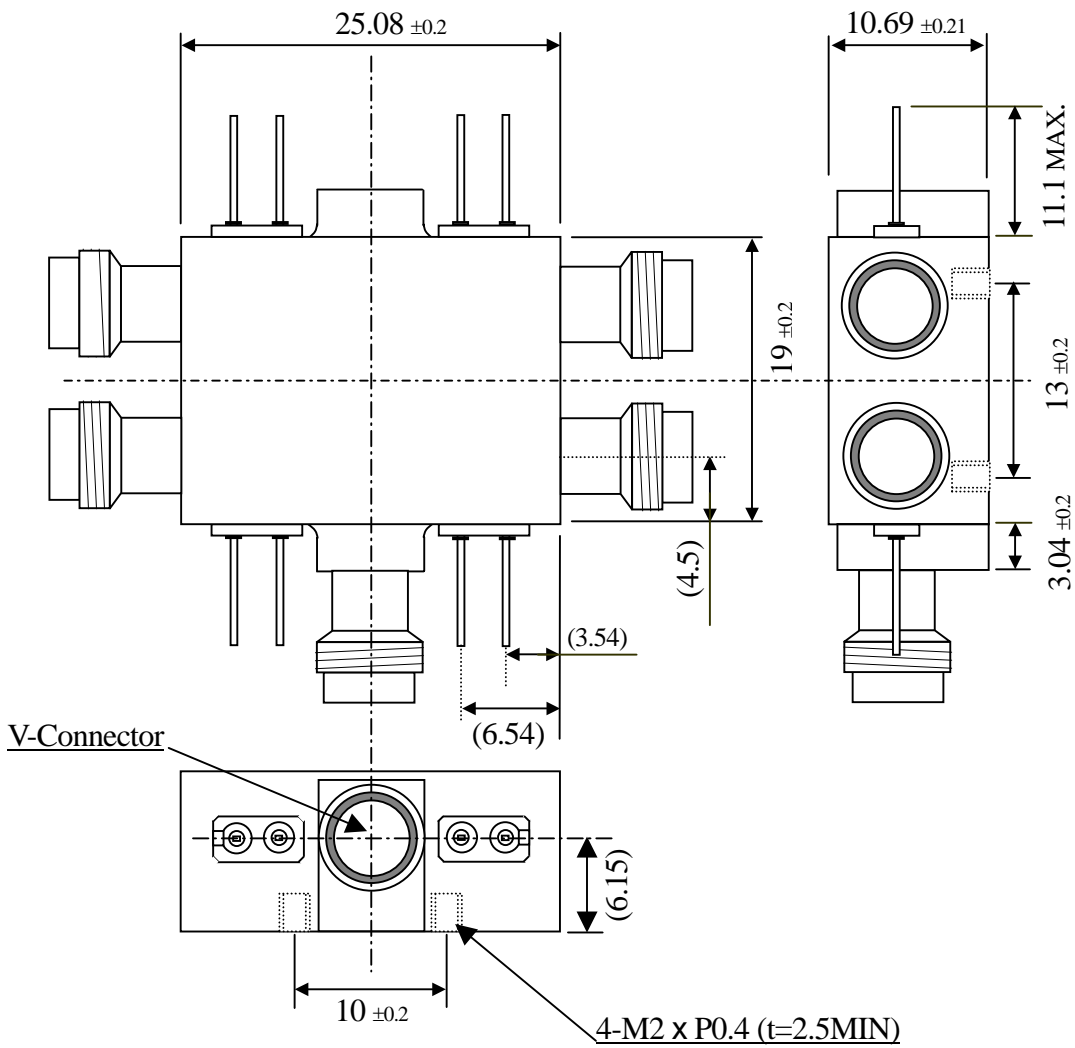
Note: Each number corresponds to a pin or a connector as shown in Connection Diagram



Note

(1) DC coupling only.

**SCMD Package Dimension (mm)**



## Handling Instructions

Since the IC is fabricated using InP HEMT process, users are recommended to follow the instructions below to prevent damage to the chip from electro-static discharge.

### (1) Power Supply Sequence

The following power sequence is recommended

- 1) Set power supply voltages  $V_{ss}$ , and GND to 0 V.
- 2) Apply  $V_{ss}$ .

RF signal is recommended to be applied, while power supplying and biasing.

### (2) Handling Precautions

- 1) Use a conductive working desk connected to the ground (or, a conductive table top connected to the ground).
- 2) Require all handling personnel to wear a conductive bracelet or wrist-strap connected to the ground through a 1 M-ohm resistor.
- 3) Ground all test equipment.
- 4) Ground all soldering iron tops.
- 5) Store IC's and other devices such as chip capacitors in their conductive carriers until they are soldered.
- 6) Use power supplies that do not generate over-voltages such as spikes. Many power supplies generate over-voltages when their outputs are turned on or turned off. To avoid these over-voltages, connect power supplies to  $V_{ss}$  after the power supply outputs are turned on and set to 0 V. Disconnect power supplies from  $V_{ss}$  after the power supply outputs are set to 0 V but before the outputs are turned off.

## Caution

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